

inserted into a circuit while allowing for end-user replacement if desired. And with Cooper Bussmann's expansive global distribution, your customers will have easy access to ensure safe, reliable, correct replacement parts available when needed.

Electrical Fuses

Cooper Bussmann® brand power fuses are the industry leader for your more demanding power applications.

From the innovative CUBEFuse™ product line – offering touch-safe, current-limiting fusible protection – to the time-honored Fusetron® product line with class-leading time-delay performance, Cooper Bussmann® fuses set the standard for motor and branch circuit protection. And now, with easyID™ technology available with the CUBEFuse™ and Low-Peak® product lines, reliable permanent open fuse indication for reduced downtime and maintenance costs.

For more delicate semiconductor drive applications, Cooper Bussmann High Speed fuses provide rapid response to damaging short circuits keeping your investment safe from damages. And look no further than the Cooper Bussmann Telpower® brand fuses for protection of critical telecommunication infrastructure.



PolySurg™ ESD Suppression Devices

Cooper Bussmann PolySurg™ ESD Suppressors are bi-directional ESD overvoltage protection devices that respond in less than 1ns and can protect against a threat voltage up to 15kV per IEC standard 61000-4-2. With leakage current of less than 1nA and an ultra low capacitance less than 0.15pF, these devices are an especially viable solution for high data rate applications. With an insertion loss of less than -0.2dB at frequencies up to 6 GHz, the PolySurg™ ESD Suppressors are invisible to the protected circuit, introducing no additional loading or signal distortion.



ESD Protection for High Frequency, Low Voltage Designs

PolySurg™ surface mount devices are ideally suited for ESD protection of data I/O ports, computers and peripherals, media interfaces (DVI and HDMI), mobile communication products, hand-held test equipment and other similar uses.

MLP Series Now Available

The MLP Series, comprised of the 0402ESDA-MLP and 0603ESDA-MLP ESD suppression devices, is now available as discrete devices in an 0402 and 0603 footprint, respectively. This series utilizes Cooper Bussmann's patented PolyFAMILY design to deliver enhanced ESD protection using state of the art process and material technologies.

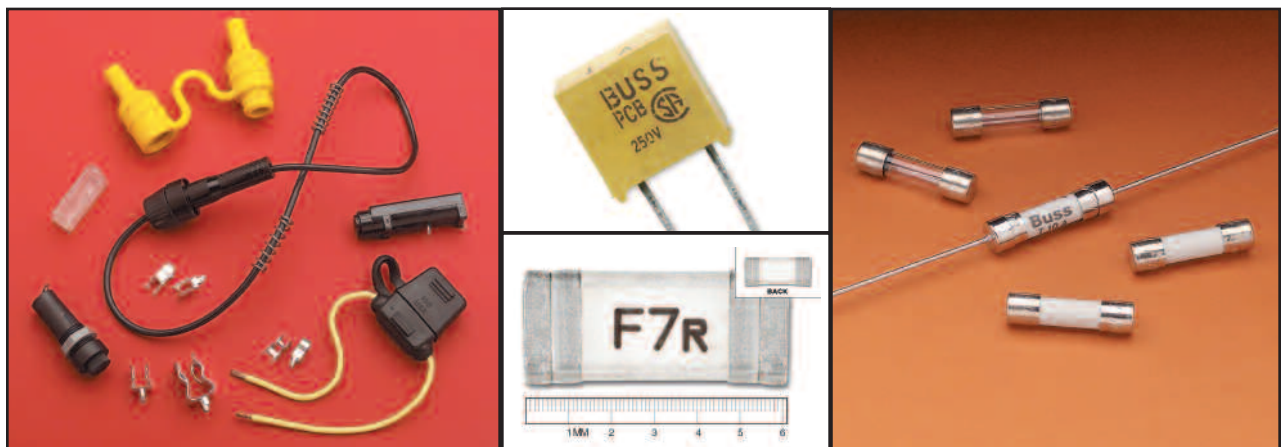


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